

Notes:

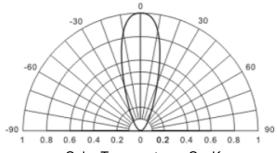
- 1000 ucd = 1 mcd, 1000 mcd = 1cd
- All dimensions are in millimenter
- Clean only in isopropanol, ethanol, Freon TF (or equivalent)
- If forming is required, it must be done before soldering. Form pin leads by securing under 5mm from body and bedding wth radio pliers or the equivalent to avoid pressure on resin. When the LED is mounted into a P.C. board, pitch spacing should be aligned to prevent any stress to the resin. Any unsuitable stress applied to resin may break bonding wire in LED, which will cause failure.
- Protruded resin under flange is 1.5mm Max.
- Specifications are subjet to change without nice.

Absolute Maximum Rating

Parameter	Maximum Rating	Unit	
DC forward current	30	mA	
Peak forward current Pulse width Max. 10ms duty ratio Max 1/10	100	mA	
Reverse Voltage	5	V	
Power dissipation	100	m₩	
Operating Temperature Range	- 40 °C to +85°C		
Storage Temperature Range	-40°C to +100°C		
Lead Soldering Temperature [4mm From Body]	260℃ for 5 seconds		

Electro-Optical Characteristics (Ta=25°C)

Parameter Radiant	Test Condition	Symbol	Min.	Тур	Max.	Unit
Forward Voltage	If=20mA	Vdd	2.8	3.6	4.0	V
Color Temperature	If=20mA	Ст			10000	K
Luminous Intensity	If=20mA	Iv	80		110	cd
Reverse Current	Vr=5V	Ir	1		100	μА
Viewing Angle	If=20mA	2 θ 1/2		20		deg



Color Temperature CT K